

1
2 **ABSTRACT**

3 A chemical mechanical polishing slurry and method for using the slurry for
4 polishing copper, barrier material and dielectric material that comprises a first and second
5 slurry. The first slurry has a high removal rate on copper and a low removal rate on
6 barrier material. The second slurry has a high removal rate on barrier material and a low
7 removal rate on copper and dielectric material. The first and second slurries at least
8 comprise silica particles, an oxidizing agent, a corrosion inhibitor, and a cleaning agent.
9